

NDIA Firepower Symposium

Common Guidance Common Sense – 16 Jun 2004

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Low Cost, High-g MEMS-IMU ...for Precision Strike

Technology & Manufacturing Development

FY01 FY02 FY03 FY04 FY05 FY06 FY07

Today: Large volume, expensive, operation in Low g environment only

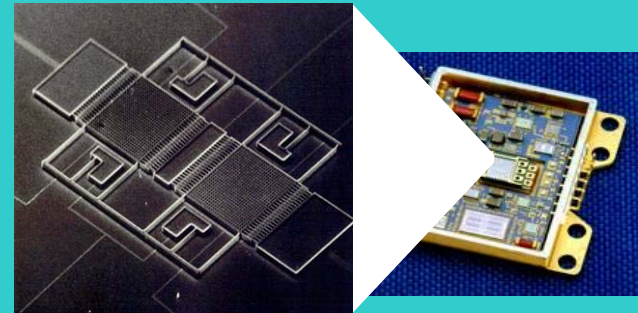


Honeywell HG-1700

Weight: 2 lbs
Volume: 33 cu in
Power: < 8 Watts
Bias Stability: 1 deg/hr
Shock: 10 - 100 g

Economy
of
Scale

High G: Tightly packaged, low cost, extremely small, tactical performance IMU/DIGNU suitable for munitions, missiles, personnel guidance and other applications



MEMS-IMU/GPS

Weight: ~ 0.5 lbs
Volume: < 2 cu in
Power: < 3 Watt
Bias Stability: 1 deg/hr
Shock: 20,000g

Same performance

>100 X G survivability

62.5% Reduction in Power Rqmts

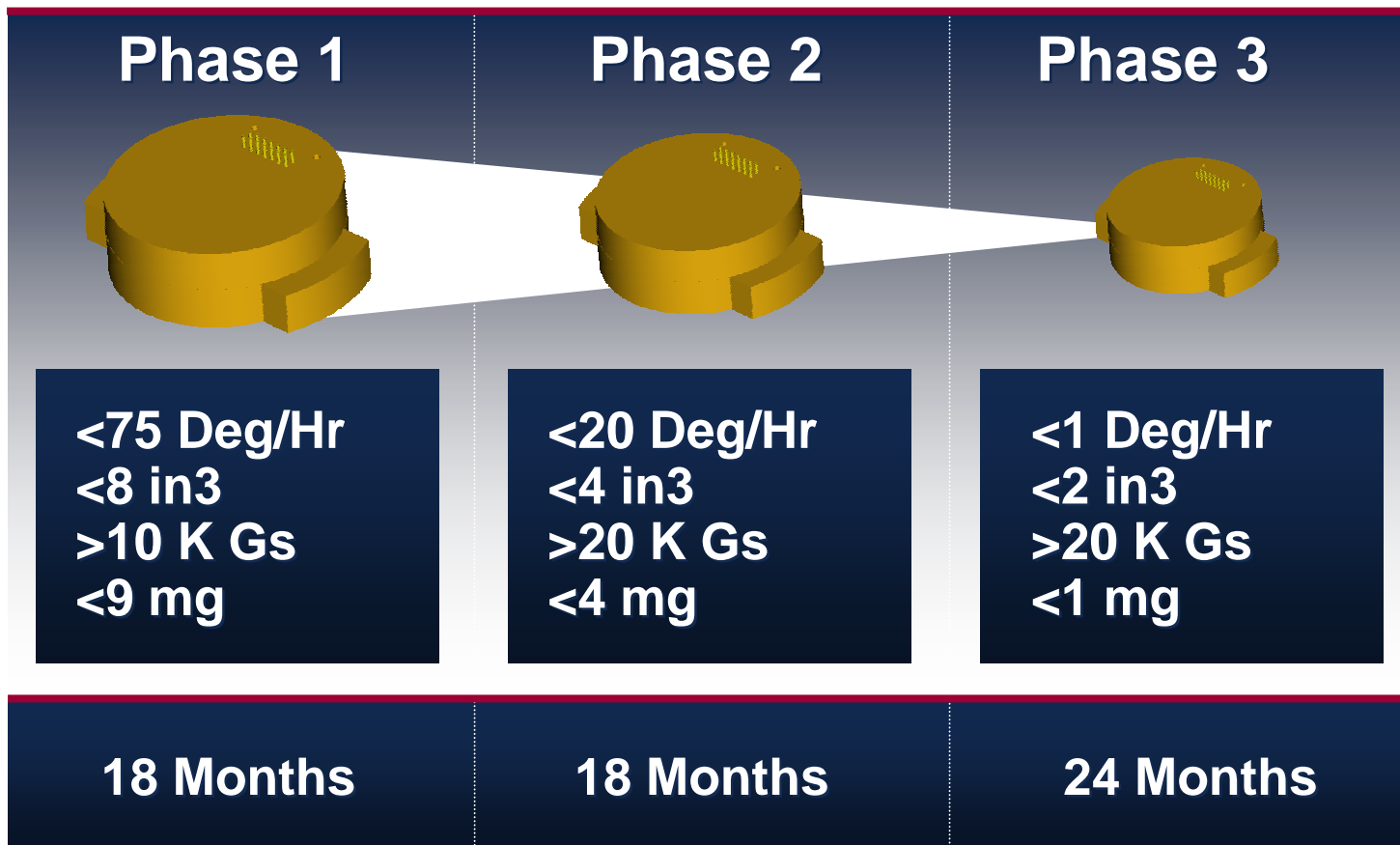
75% Reduction in IMU Weight

> 90% Reduction in IMU Volume

76% Reduction in Cost (\$1.2K per IMU)

Meets Accuracy & Size Needs for >90% DoD Precision Weapons

High-G MEMS IMU Evolution



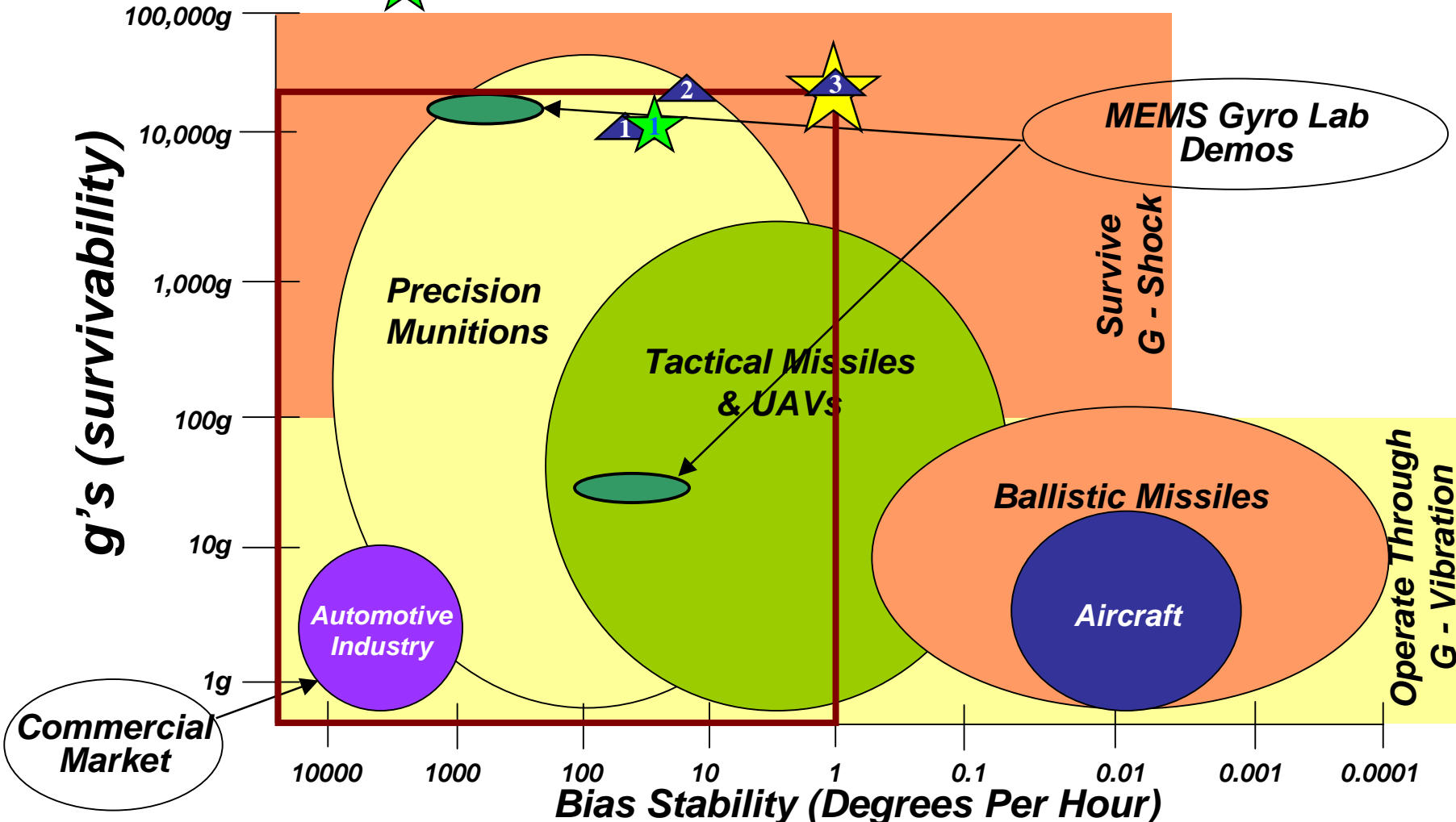
Incrementally Shrink Volume and Power While Improving Performance

IMU Performance Demands



Desired Performance per Phase

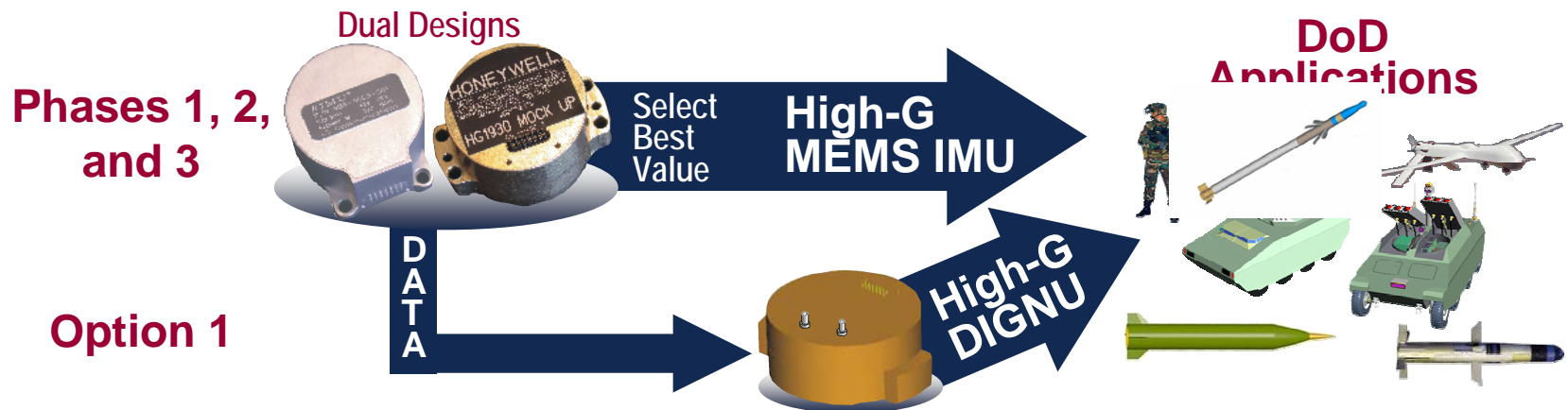
Actual Performance per Phase



Technology and Manufacturing Program Launched
affordable, high-g, Precision IMU & IMU/GPS

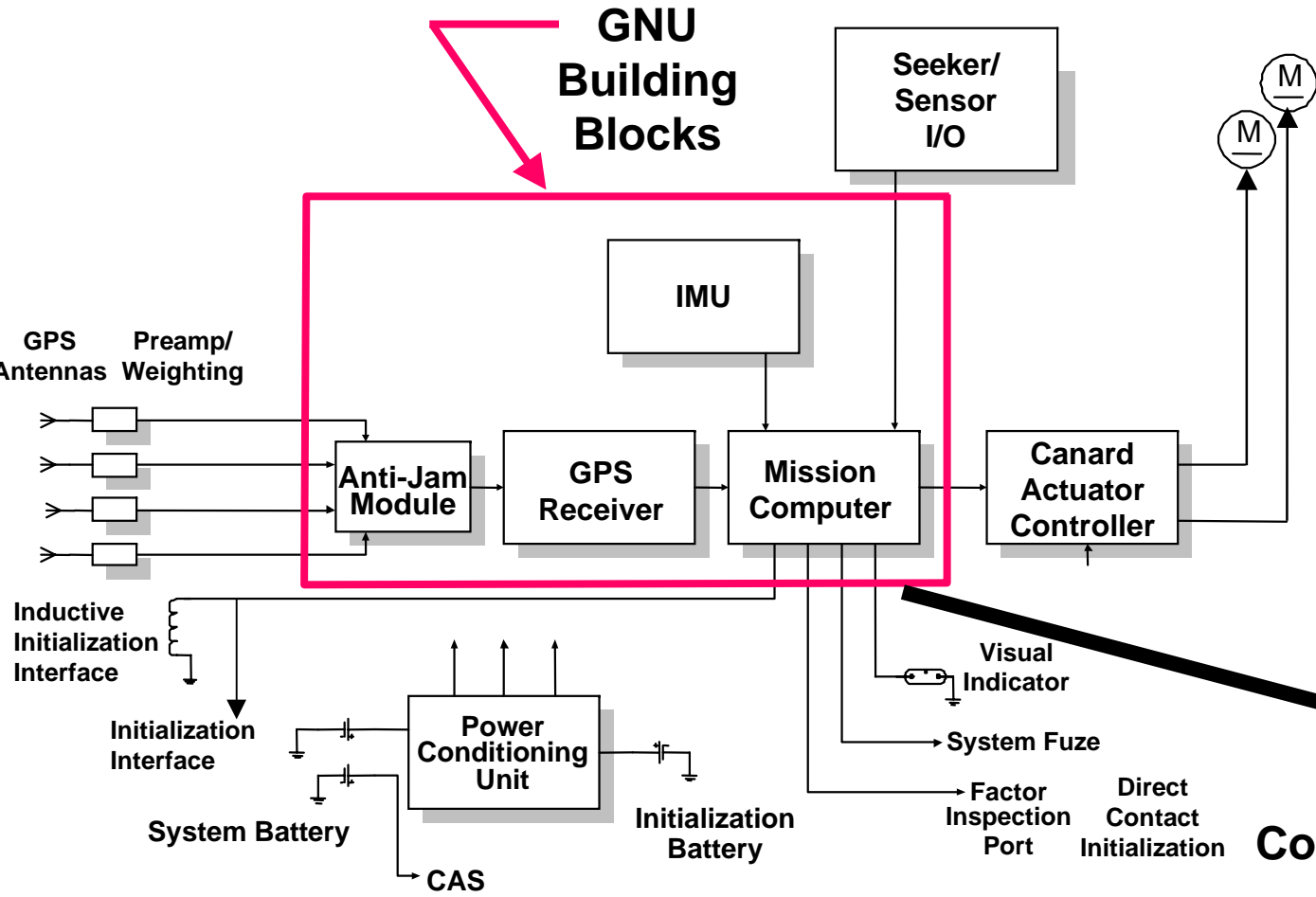
Program/Business Strategy

- **Go To Multiple IMU Design / Manufacturing Teams**
 - L3/IEC
 - Honeywell/Draper/Rockwell Collins
- **Build to Common Requirement**
- **Leverage Process Improvements into Multiple DoD Applications**
- **Teams Incorporate Common IMU into Common, Deeply Integrated (GPS/IMU/AJ) Guidance & Navigation Unit (DIGNU) Built to Common Specification**

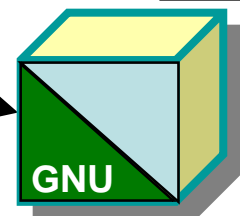


Typical GN&C Functional Block Diagram

Typical
As used in:
APKWS, XM982,
PGMM, GMLRS,
LCCM, MRAAS,
QuickLook,
TERM, MRM,
AGS, ERGM,
TCM



Building Block of the Future

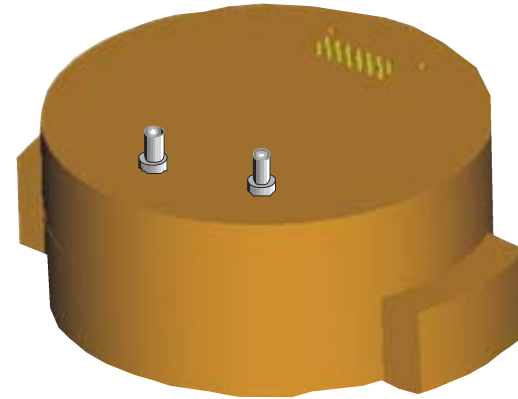


Common Guidance & Navigation Unit (GNU) Module Single Processor Architecture

Currently, Each Subassembly Represents One or More Circuit Card Assemblies, Each With One or More Processors

Deeply Integrated Guidance and Navigation Unit (DIGNU)

- **Traditional GPS/INS Integration Enhances A/J Loss of Lock Capability**
- **Deep Integration Concept Provides 15-20 db A/J Over Conventional Tightly Coupled Solutions (SW Solution Only)**
- **Improves Weapon Effectiveness by Decreasing CEP**
- **Common Interface Control Document (ICD)**
- **Single Processor Architecture**
- **Higher Reliability**



**Knowing Where You Are
And Where You Need To Be**

Technology Investment Areas

S & T

PERFORMANCE DRIVERS

- Size
- Weight
- Performance
- Power
- Environment
- Reliability

ManTech

COST DRIVERS

- Touch Time
- New Capital Equipment
- New Process Development
- New Product Development
- Low Volume Production

PERFORMANCE IMPROVERS

- Technology Development
 - Design
 - Test
 - Evaluate
- Improve Design
- Improve Technology

- Do It Again

COST REDUCERS

- Automation
 - Improved Consistency
 - Reduce Touch Time
- Upgrade Equipment
 - Better Control
 - Improved Yield
- Consolidate
- Economy of Scale

Using Manufacturing Technology to achieve Technical Performance Goals

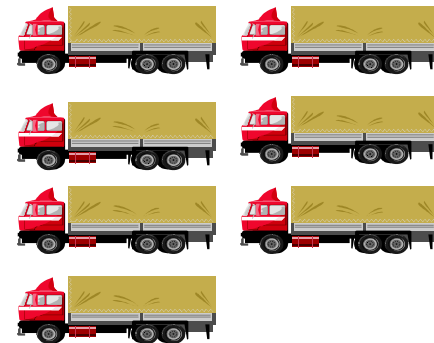
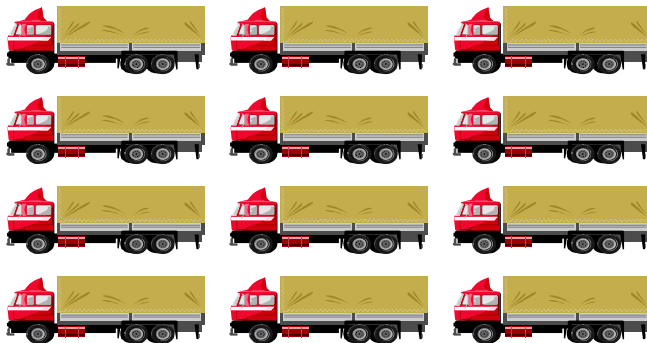
What's the Payoff

Common Guidance provides:

- common performances across multiple platforms
- cost reduction

More accuracy has a cost “ripple” effect

- fewer firings
- smaller footprint/field of view
- positive benefit on logistics



Program Output

- ***Common Interface Control Document for compatibility across multitude of platforms***
- ***Common Performance Specification for consistent output signals***
- ***Two qualified suppliers producing interchangeable devices***

**Provide Common MEMS IMU/DIGNU
for 90% of all DoD Applications**

Summary

- ***Honeywell and L3 are committed to producing MEMS IMUs for future DoD systems***
- ***Program will develop two contractors that can provide MEMS IMUs & DIGNUs for the military at program completion***
- ***Utilizing ManTech dollars allows program to achieve aggressive S & T goals***
- ***Next public presentation of the ICD and performance specification to potential end users will occur at the MEMS IMU Industry Day targeted for September 2004***